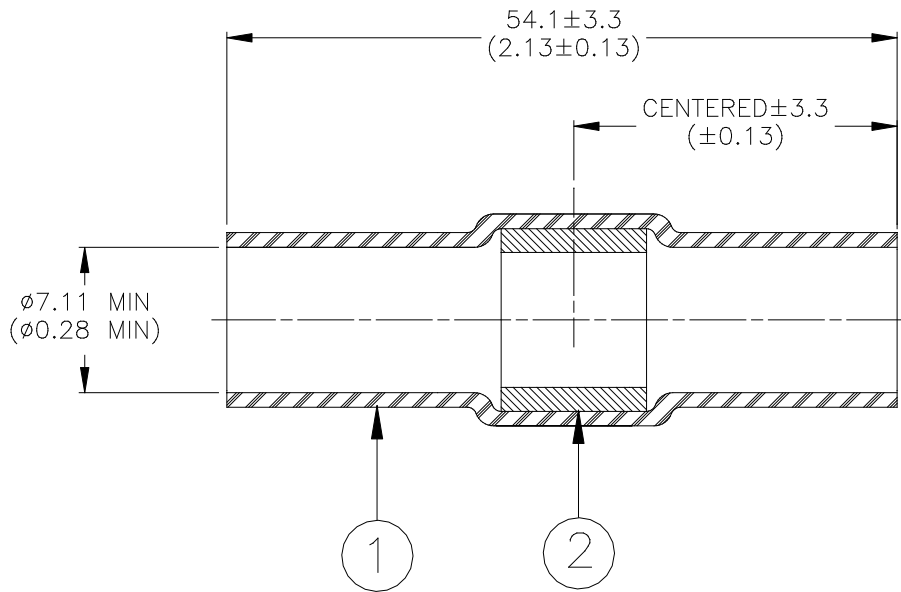


CUSTOMER DRAWING




MATERIALS

1. INSULATION SLEEVE: Heat-shrinkable, transparent blue, radiation cross-linked modified polyvinylidene fluoride.
2. SOLDER PREFORM WITH FLUX:
 - SOLDER: TYPE Sn63 per ANSI J-STD-006.
 - FLUX: TYPE ROM1 per ANSI-J-STD-004.

APPLICATION

1. This part is designed to make a non-sealed in-line splices in conductors.
 - Splice Criteria:
 - Conductor Type: Bare or tin plated copper.
 - Circular Mil Range: 9,000 to 13,000.
 - Insulation Diameter: 3.56 – 7.11 (0.14 to 0.28).
2. Wires are to be stripped 19.1 – 25.4 (0.75 to 1.00) and overlapped under the solder preform.
3. Part may be installed with TE Connectivity/Raychem hot air or infrared heaters.
4. Part will meet requirements of Raychem Specification RT-1404.

		Raychem THERMOFIT DEVICES	TITLE: SOLDERSLEEVE WIRE SPLICE, IN-LINE, NON SEALED		
Unless otherwise specified dimensions are in millimeters. [Inches dimensions are shown in brackets]			DOCUMENT NO.: <div style="text-align: center; font-weight: bold; font-size: 1.2em;">D-110-0100</div>		
TOLERANCES: 0.00 N/A 0.0 N/A 0 N/A	ANGLES: N/A ROUGHNESS IN MICRON	TE Connectivity reserves the right to amend this drawing at any time. Users should evaluate the suitability of the product for their application.	REV : <div style="text-align: center; font-weight: bold;">2</div>	DATE : <div style="text-align: center; font-weight: bold;">17-APR-2020</div>	
DRAWN BY: M. FORONDA	DATE: 06-JUL-00	ECO: ECO-20-005247	SCALE: NTS	SIZE: A	SHEET: 1 of 1

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